

PIN ASSIGNMENT(Front)																							
A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	
GND	TX1+	TX1-	Vbus	CC1	D+	D-	SBU1	Vbus	RX2-	RX2+	GND	GND	RX1+	RX1-	Vbus	SBU2	D-	D+	CC2	Vbus	TX2-	TX2+	GND

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
C	ECN NO.:S202106-R14	XIAO	2021.07.07
D	ECN NO.:S202108-C01	XIAO	2021.09.01
E	ECN NO.:S202202-C10	XIAO	2022.03.14

SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:

- 1-1. LLCR:
 VBUS & GND PINS: 40mΩ /PIN MAX.
 OTHER PINS: 40mΩ /PIN MAX.
 LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

- 1-2. CURRENT RATING: 3.0 A Max.
 1-3. VOLTAGE RATING: 5.0 V.
 1-4. INSULATION RESISTANCE: 100MΩ MIN.
 1-5. ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -55°C+85°C.

2. MECHANICAL CHARACTERISTICS:

- 2-1. MATING FORCE : 5-20 N.
 2-2. UNMATING FORCE : 14N Min. After test 8N Min.

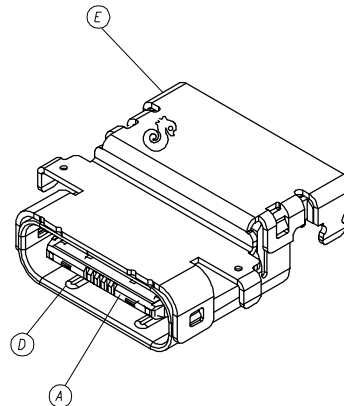
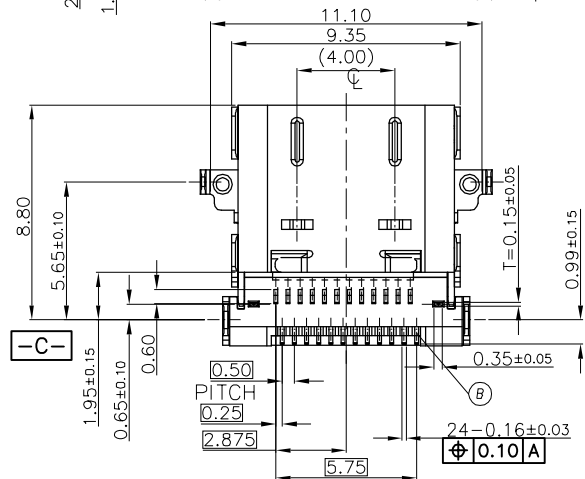
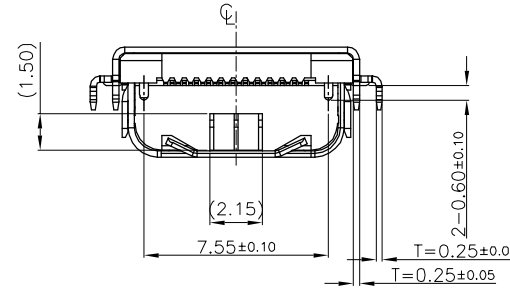
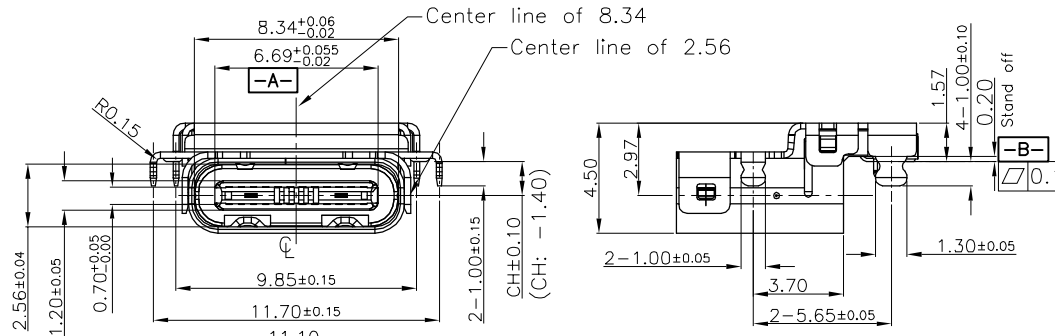
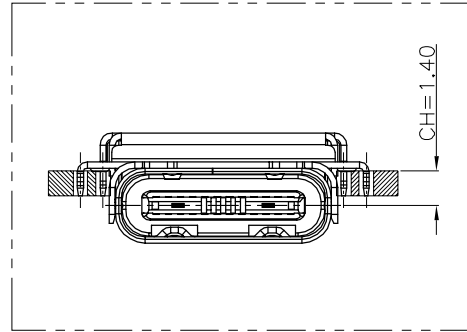
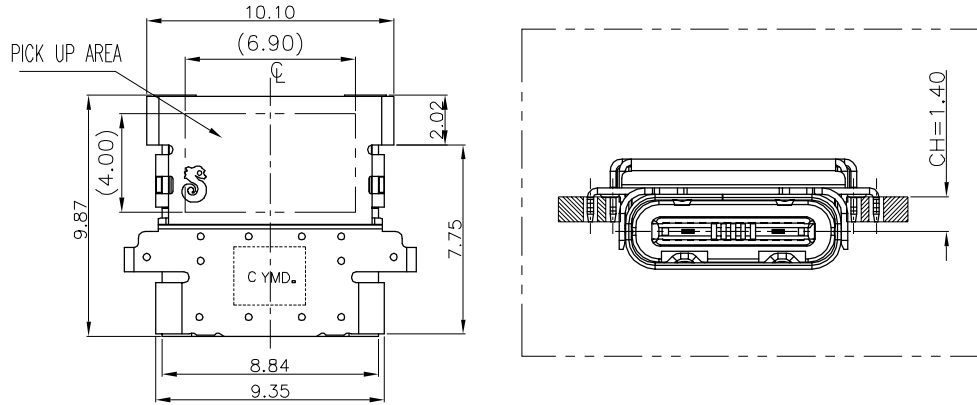
3. LIFE TEST: 10000 CYCLES MIN.

4. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.

5. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: Ⓢ

6. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: Ⓢ

7. FOR REFLOW SOLDERING LEAD-FREE PROCESS.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	TOP SHELL	1	STAINLESS STEEL,T=0.25	80μin Min. Solderable Nickel plating.
D	SHELL	1	STAINLESS STEEL,T=0.25	80μin Min. Solderable Nickel plating.
C	MID-GND	1	SUS301 T=0.15	N/A
B	CONTACT	24	C7025 T=0.12	30μin Min. Gold plating on contact area. G/F plating on solder tail area. 80μin Min. NICKEL under plating.
A	BODY	1	LCP E471i UL94-V0	BLACK
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE		
X	:±0.5	X	:±2°	DWN xiao
X.X	:±0.3	X.X	:±1°	CHKD allen
X.XX	:±0.2			APVD boye
		USB TYPE -C Dual SMT (C.H.=-1.40) TBT4 PART NO: 2UB3C39-000111F SCALE:4:1 UNIT: mm SIZE: A3 SHEET:1 OF 2 REV: E		
CUSTOMER COPY				

